STANDARD FEATURES L-1520e

- Menu Driven Software
- Programmable Z head control
- Programmable XY stage
- Programmable dispense time
- Programmable delay time
- Programmable leadframe pitch
- Programmable pressure regulator
- 600" to 3.150" leadframe Capability
- 250 Program Storage
- Status Tower / Green-Yellow-Red
- Fast product change over
- Single magazine elevator
- Built in diagnostics
- Allteq reliability

SPECIFICATIONS

PHYSICAL

Weight:	135 lbs.
Depth:	24 inches
Width:	33 inches
Height:	14 inches (less tower)
Tower:	add 20"

FACILITIES

Power:	115/230V 250W 50/60Hz
Air:	70 PSI Min

ELECTRONICS

Microprocessor:	68331
Battery backup:	10 Year
Display:	2 x 40

MECHANICAL

X Travel:	1.40"
Y Travel:	2.40"
Z Travel:	1.10"
Leadframe Width:	.600" to 3.150"
Indexer Accuracy:	+/- .004"
Frame Changeover:	60 Sec.

OPERATIONS

Cycle Time: 7000 UPH (10 Device Leadframe)

The 1500 Series Runs a wide range of matirial inculding but not limited to products from Dow Corrning

Dow Corning® Brand Product	Description	Features	Potential Uses
HIPEC® R 6101 Semiconductor Protective Coating	1-part heat cure clear, good flowability, soft elastomer, self priming adhesion	Excellent adhesion, light transmission, flexible at high and low temperatures	Protection of discrete devices such as transistors and rectifiers
HIPEC® R 6102 Semiconductor Protective Coating	1-part heat cure black, good flowability, soft elastomer, self priming adhesion	Excellent adhesion, blockage for light sensitive devices, flexible at high and low temperatures	Protection of discrete devices such as transistors and rectifiers
Dow Corning® JCR 6224	1-part, heat cure black, thixotropic, DRAM grade	Excellent workability, long pot life at room temperature, excellent printing capability; excellent adhesion, thermal stability and electrical properties	Good flowability encapsulant for chip scale packages that require DRAM-grade purity
HIPEC ® Q1-4939 Semiconductor Protective Coating	2-part clear heat cure, cures to elastomer or gel depending on mix ratio, good flowability	Solventless silicone gel or elastomer; protection from thermo-mechanical shock	Sealing, preserving and protecting complex, integrated circuits
HIPEC® Q1-9239 Semiconductor Protective Coating	1-part, black heat cure, controlled thixotropy-flowable as dispensed, self priming adhesion	Fast heat cure; excellent adhesion; flexible over wide temperature range	For applications where a semiconductor die has been wire bonded to a flat surface
HIPEC ® Q3-6646 Semiconductor Protective Coating	2-part clear heat cure gel, very low viscosity, long working time, enhanced low temp capability	Solventless silicone gel or elastomer; protection from thermo-mechanical shock	Sealing, preserving and protecting complex, integrated circuits